



Date: August 25th, 2014

Engineering Change Notice

ECN #: 1010

Title: MRF555 Die periphery increased

Change Category: Requires customer notification & customers are encouraged to evaluate samples prior to placing production orders

As of August 25th 2014 ASI has made a permanent change to the RF die. The die periphery has been increased by 50% to improve the compatibility of the ASI MRF555 with the original device and circuits designed for the original device.

The change will increase the input and output capacitances of the device, improve the thermal performance and improve ruggedness of the device. None of the improvements result in a specification change because all specifications are still within the ranges stated in the data sheet.

Products Impacted:

MRF555
MRF555T
MRF555LF
MRF555TLF